



FORM PTO-1449 (MODIFIED)

LIST OF PATENTS AND
PUBLICATIONS
FOR APPLICANTS INFORMATION
DISCLOSURE STATEMENT

ATTORNEY DOCKET NO.

SP01-302

SERIAL NO.

10/035659

APPLICANT: COOK, et al.

FILING DATE 10/26/2001

GROUP: 1731

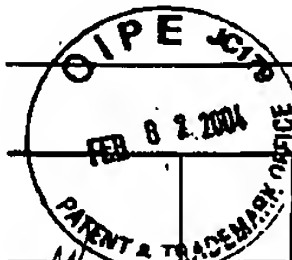
REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub- Class	Filing Date if Approp.
JL	AA	4,186,999	2/5/80	Harwood et al	350	96.21	
	AB	4,530,452	7/23/85	Balyasny et al	225	96	
	AC	4,626,068	12/2/86	Caldwell	350	96.34	
	AD	5,183,710	2/2/93	Gerbino	428	405	
	AE	5,346,583	9/13/94	Basavanhally	156	629	
	AF	5,451,547	9/19/95	Himi et al	437	225	
	AG	5,452,122	9/19/95	Tsuneda et al	359	281	
	AH	5,579,421	11/26/96	Duvall et al	385	14	
	AI	5,631,986	5/20/97	Frey et al	385	78	
	AJ	5,846,638	12/8/98	Meissner	428	220	
	AK	5,852,622	12/22/98	Meissner et al	372	39	
	AL	5,989,372	11/23/99	Momoda et al	156	89.11	
	AM	6,030,883	2/29/00	Nishimoto et al	438	455	
	AN	6,048,103	4/11/00	Furukata et al	385	73	
	AO	6,249,619	6/19/01	Bergmann et al	385	11	
	AP	6,275,336	8/14/01	Yoshikawa et al	359	484	
	AQ	6,359,733	3/19/02	Iwatsuka et al	359	500	
	AR	6,583,029	6/24/03	Abe et al	438	455	
	AS	2002/0108556	8/15/02	Ebbers	117	2	
	AT	2003/0079503	5/1/03	Cook et al	65	407	
	AU	2003/0079823	5/1/03	Sabia	156	99	
	AV	2003/0081906	5/1/03	Filhaber et al	385	60	
	AW	2003/0206345	11/6/03	Sabia et al	359	484	
	AX	2003/0206347	11/6/03	Sabia et al	359	484	
	AY	2003/0081930	5/1/03	Filhaber et al	385	147	
	AZ	4,960,331	10/2/90	Goldman et al	356	350	
V	A1	5,319,483	6/7/94	Krasinski et al	359	113	
	A2	5,441,803	8/15/95	Meissner	428	220	
	A3	5,689,519	11/18/97	Fermann et al	372	18	
	A4	6,120,917	9/19/00	Eda	428	692	
	A5	6,548,176	4/15/03	Gwo	428	420	
	A6	6,621,630	9/16/03	Iwatsuka	359	484	

Information Disclosure Statement-PTO-1449 (Modified)

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	SP01-302	10/035659
	APPLICANT: COOK, et al.	
	FILING DATE 10/26/2001	GROUP: 1731



FOREIGN PATENT DOCUMENTS

	Document Number	Date	Country	Class	Sub-Class	Translation Yes No	
AA	WO01/98225	12/27/01	PCT	C03C	27/06		
AB	WO00/17698	3/30/00	PCT	G02F	1/09		
AC	DE19731075	1/21/99	Germany	C03C	29/00		Relevance?
AD	DE2130905	1/11/73	Germany	H01j	19/56		Relevance?
AE	08-146351	6/7/96	Japan (English Abstract)	G02B	27/28		
AF	2002321947	4/25/01	Japan (English Abstract)	C03C	27/00		
AH	03-115178	5/16/91	Japan (English Abstract)	C04B	37/00		

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

AI	ONISHI et al., "A novel temperature compensation method for SAW devices using direct bonding Techniques," <i>Ultrasonics Symp</i> , 1997, IEEE Proceedings, 5-8 Oct, 1997 Pages 227-230.
AK	Arthur Landrock; "Surface Preparation of Adherends"; Adhesives Technology Handbook, 1985; page 117-118 <i>CANT Read - Poor quality</i>

EXAMINER:

DATE CONSIDERED:

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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	APPLICANT Cook et al.	
	FILING DATE: Herewith	GROUP: To Be Assigned

10/035659
 10/26/01

REFERENCE DESIGNATION				U.S. PATENT DOCUMENTS			
Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
<i>[Signature]</i>	AA	5,915,193	6/22/99	Tong et al.	438	455	
	AB	5,785,874	7/28/98	Eda	216	24	
	AC	5,932,048	8/3/99	Furukawa et al.	156	153	
	AD	6,129,854	10/10/00	Ramsey et al.	216	18	
	AE	6,153,495	11/28/00	Kub et al.	438	459	
	AF	6,178,779	1/30/01	Drouart et al.	65	391	
	AG	6,098,429	8/8/01	Mazabraud et al.	65	392	
	AH	4,407,667	10/4/83	LeNoane et al.	65	3.11	

FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Sub-Class	Translation Yes No
<i>[Signature]</i>	AI	1 057 793A1	12/6/00	EPO	C03B	37/027	X

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)		
<i>[Signature]</i>	AJ	A. Sayah, D. Solignac, T. Cueni, "Development of novel low temperature bonding technologies for microchip chemical analysis applications," Sensors and Actuators, 84 (2000) pp. 103-108. <i>IN complete date</i>
<i>[Signature]</i>	AK	P. Rangsten, O. Vallin, K. Hermansson, Y. Backlund, "Quartz-to-Quartz Direct bonding," J. Electrochemical Society, V. 146, N. 3, pp. 1104-1105, 1999).
<i>[Signature]</i>	AL	H. Nakanishi, T. Nishimoto, M. Kani, T. Saitoh, R. Nakamura, T. Yoshida, S. Shoji, "Condition Optimization, Reliability Evaluation of SiO ₂ -SiO ₂ HF Bonding and Its Application for UV Detection Micro Flow Cell," Sensors and Actuators, V. 83, pp. 136-141, 2000. <i>IN complete date</i>
<i>[Signature]</i>	AM	A. Yamada, et al., Bonding Silicon wafer to Silicon Nitride With Spin-on Glass Adhesive, Electronics Letters, March 26, 1987, Vol. 23, No. 7. ✓
<i>[Signature]</i>	AN	D.J. Harrison, et al., Micromachining a Miniaturized Capillary Electrophoresis-Based Chemical Analysis System on a Chip, Science 261 (1993) 895-897. ✓
<i>[Signature]</i>	AO	W.P. Maszara, Silicon-on-insulator by Wafer Bonding: A Review, J. Electrochemical Society 138 (1991) 341-347. ✓
<i>[Signature]</i>	AP	D-W. Shin, et al., The Stacking Faults and Their Strain Effect at the Si/SiO ₂ Interfaces of a Directly Bonded SOI (silicon on insulator), Thin Solid Films, V. 346, pp. 169-173, 1999. ✓
<i>[Signature]</i>	AQ	Q-Y. Tong, et al., The Role of Surface Chemistry in Bonding of Standard Silicon Wafers, J. Electrochemical Society V. 144, N. 1, pp. 384-389, 1997 <i>January</i>

EXAMINER: *[Signature]* DATE CONSIDERED: *5-04*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609: draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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10/035,659

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DISCLOSURE STATEMENT

APPLICANT Cook et al.

FILING DATE October 26, 2001

GROUP: To Be
Assigned

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

Examiner Initial		Document Number	Date	Name	Class	Sub- Class	Filing Date if Approp.
	AA						
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FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub- Class	Translation Yes No
JA	AL	52[1977]-78450	7/1/77	Japan	G02B	5/14	X
	AM						
	AN						
	AO						
	AP						
	AQ						

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

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EXAMINER:

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5-2007

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	AA						
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FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							
	AQ							

OTHER ART (Including Author, Title, Date, Pertinent Pages, etc.)

	AR	Andreas Plobl et al., Wafer Direct Bonding: Tailoring Adhesion Between Brittle Materials, Materials Science and Engineering, R25 (1999) pp. 1-88.
	AS	
	AT	
	AU	
	AV	
	AW	

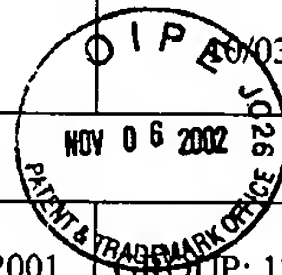
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5-26-04

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	APPLICANT Cook et al.	
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Examiner Initial		Document Number	Date	Name	Class	Sub-Class	Filing Date if Approp.
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FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Sub-Class	Translation Yes No	
	AL	P2000 56265A	2/25/00	Japan	G02B	27/28	X	
	AM							
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	AO							
	AP							
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5-2004

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